Company Presentation

November 12, 2013

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- **Market and Business Development Fourth Quarter FY 2013**

- **Business Focus**

- **Segments, Products and Technology**

- **General Company Information**

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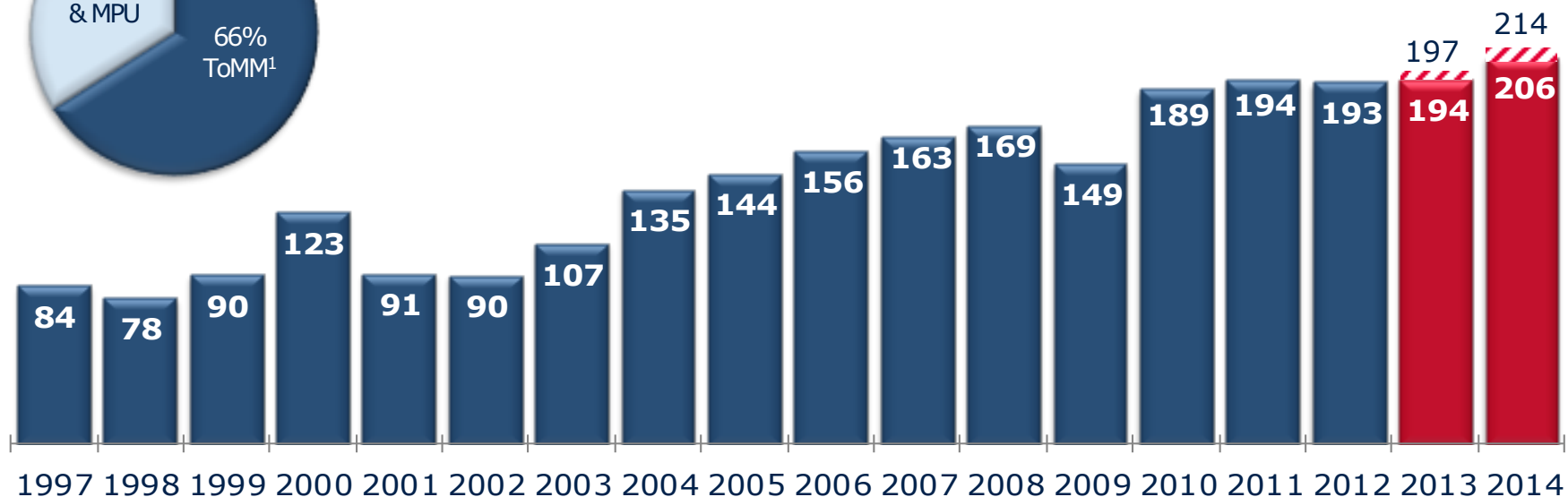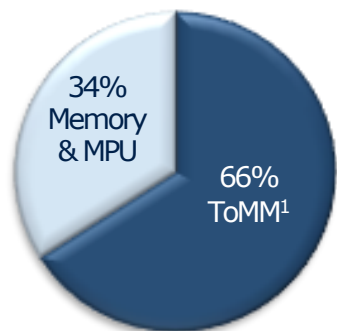
Positive Growth Outlook
for Global Semiconductor Market

Global Semiconductor Market *w/o Memory, w/o Microprocessor*
in Billion US-Dollar

2012: $ 292 bn

34%
Memory
& MPU

66%
ToMM[1]

1997	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
84	78	90	123	91	90	107	135	144	156	163	169	149	189	194	193	194 / 197	206 / 214

■ Market size (revenue)   ◆▨ Forecast revenue range

[1] ToMM: Global semiconductor market w/o Memory, w/o Microprocessor; 2/3 of the total semiconductor market are relevant for our 4 segments
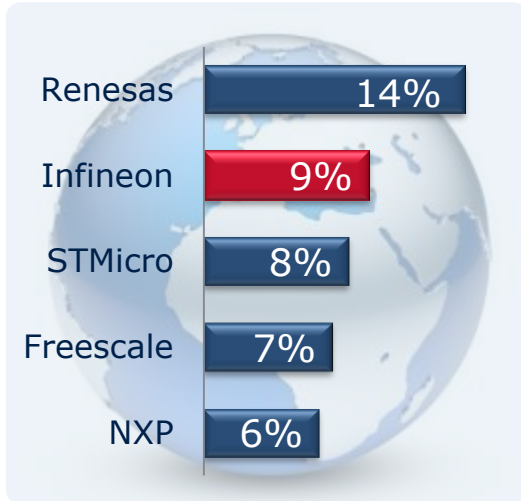Source: WSTS for historical data. Forecast: ∅ of WSTS, IHS, Gartner, IC Insights; last update November 4, 2013

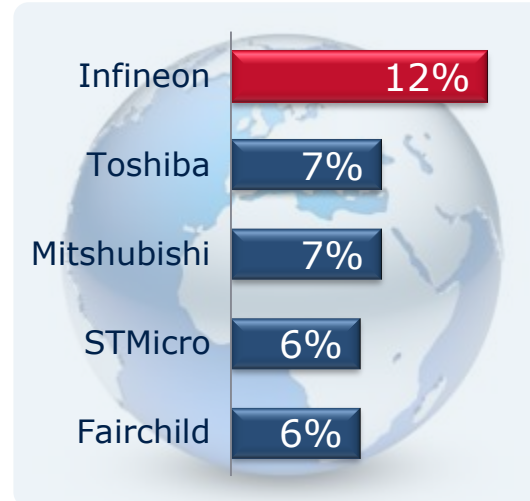# Infineon Holds Top Positions in All Target Markets

Automotive

#2

Renesas	14%
Infineon	9%
STMicro	8%
Freescale	7%
NXP	6%

Automotive semiconductors in calendar year 2012.

Source: Strategy Analytics, April 2013.

Power

#1

Infineon	12%
Toshiba	7%
Mitshubishi	7%
STMicro	6%
Fairchild	6%

Power semiconductors and modules in calendar year 2012.

Source: IHS, September 2013.

Chip Card

#1

Infineon	24.1%
NXP	23.8%
Samsung	22%
STMicro	17%
SHHIC	6%
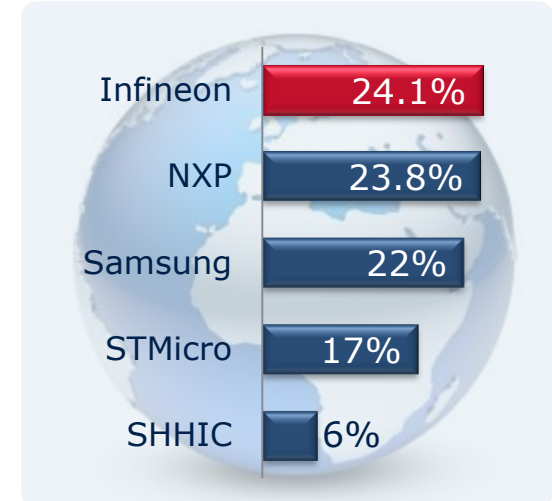
Microcontroller-based smart card ICs in calendar year 2012.

Source: IHS, September 2013.

Infineon at a Glance

The Company

- Infineon provides semiconductor and system solutions, focusing on three central needs of our modern society: Energy Efficiency, Mobility and Security

- Revenue in FY 2013: € 3.843 billion

- 26,725 employees worldwide (as of September 2013)

- Strong technology portfolio with more than 18,650 patents and patent applications (as of September 2013)

- More than 20 R&D locations

- Germany's largest and Europe's second largest semiconductor company

Infineon Group
Results for FY 2013 vs FY 2012

Revenues	Net Income
-2%	
3,904 **3,843**	**427** **272**
FY12 FY13	FY12 FY13
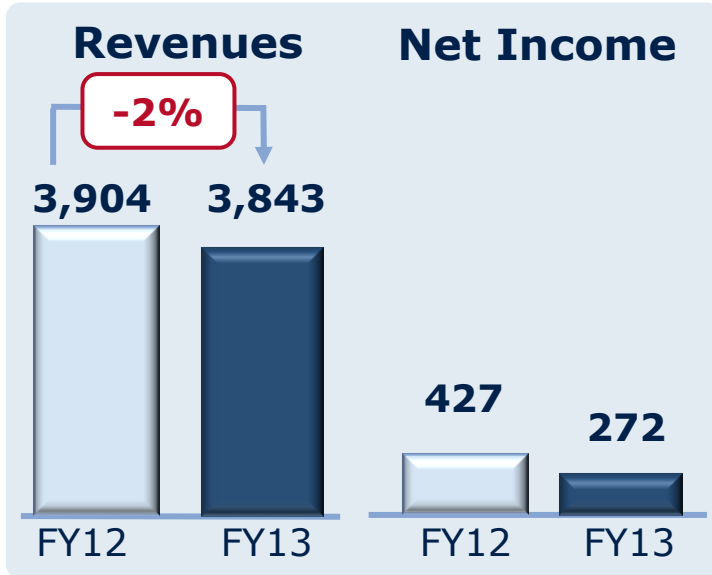
in € Million	2012	2013	
Revenues	3,904	3,843	⬇
Segment Result (SR)	527	377	⬇
SR Margin	13.5%	9.8%	⬇
Net Income	427	272	⬇
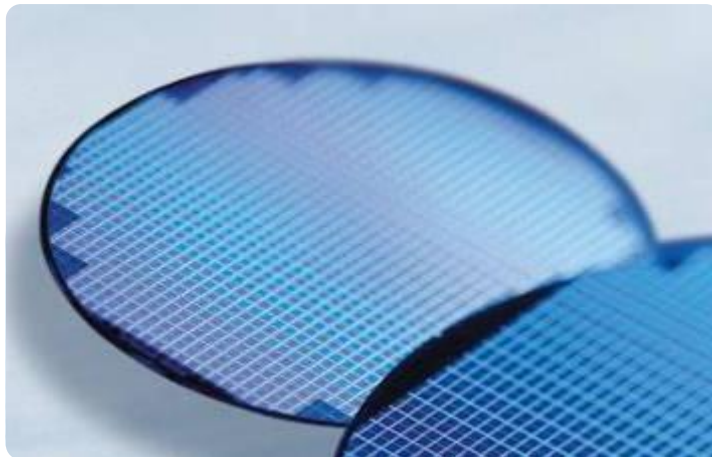
	2012	2013	
Free Cash Flow	-219	235	⬆
Investments	890	378	⬇
Net Cash	1,940	1,983	⬆
Market capitalization	~5,335	~7,995	⬆

Infineon Group
Results for Q4 FY13 vs Q3 FY13

Revenues   Net Income

+3%

1,022   1,053

142

77

☐ Q3 FY13   ■ Q4 FY13
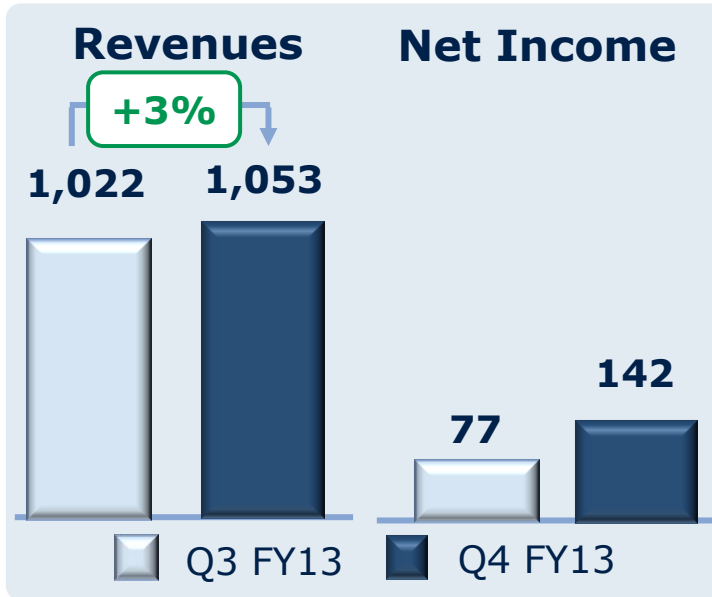
in € Million	Q3 13	Q4 13	
Revenues	1,022	1,053	⬆
Segment Result (SR)	117	148	⬆
SR Margin	11.4%	14.1%	⬆
Net Income	77	142	⬆
Free Cash Flow	135	156	⬆
Gross Cash Position	2,137	2,286	⬆
Net Cash	1,835	1,983	⬆

Infineon Group
Results for Q4 FY13 vs Q4 FY12

Revenues   Net Income

+7%
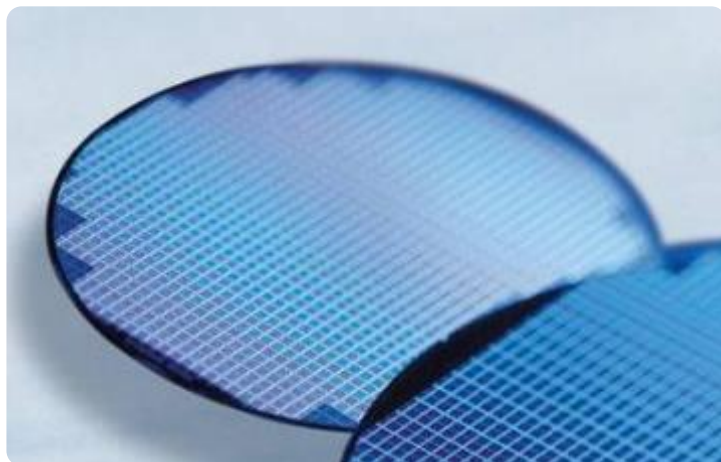
982   1,053

138   142
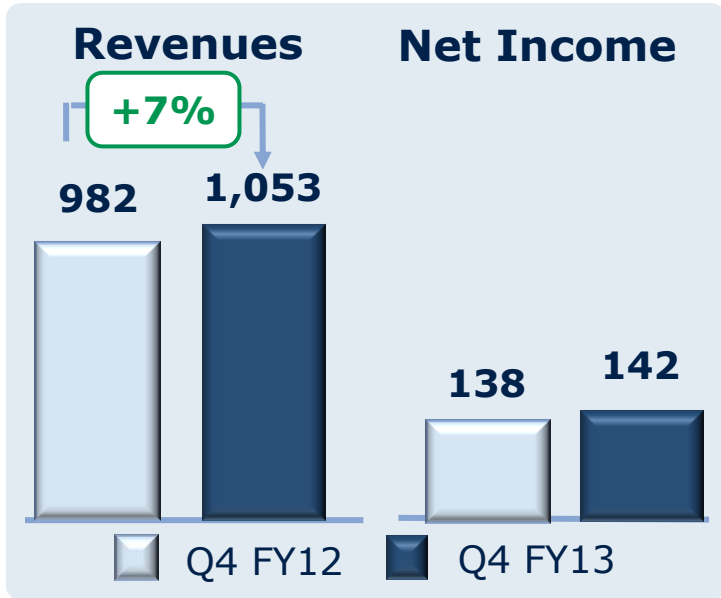
Q4 FY12   Q4 FY13

in € Million	Q4 12	Q4 13	
Revenues	982	1,053	
Segment Result (SR)	116	148	
SR Margin	11.8%	14.1%	
Net Income	138	142	

Free Cash Flow	47	156	
Gross Cash Position	2,235	2,286	
Net cash	1,940	1,983	
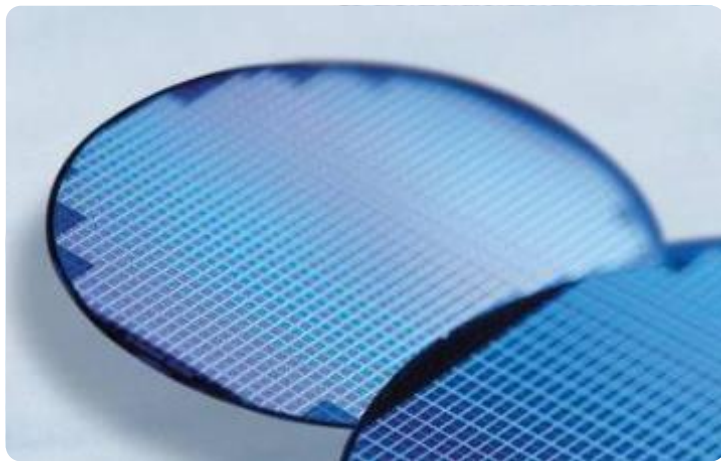
Infineon Segment Revenues
Q4 FY13 vs Q3 FY13

Revenue* in € Million

Segment		Q3 FY13	Q4 FY13	Change
ATV		459	455	-1%
IPC		173	197	+14%
PMM		266	271	+2%
CCS		119	129	+8%

Share of Total

- ATV: 43%
- IPC: 19%
- PMM: 26%
- CCS: 12%
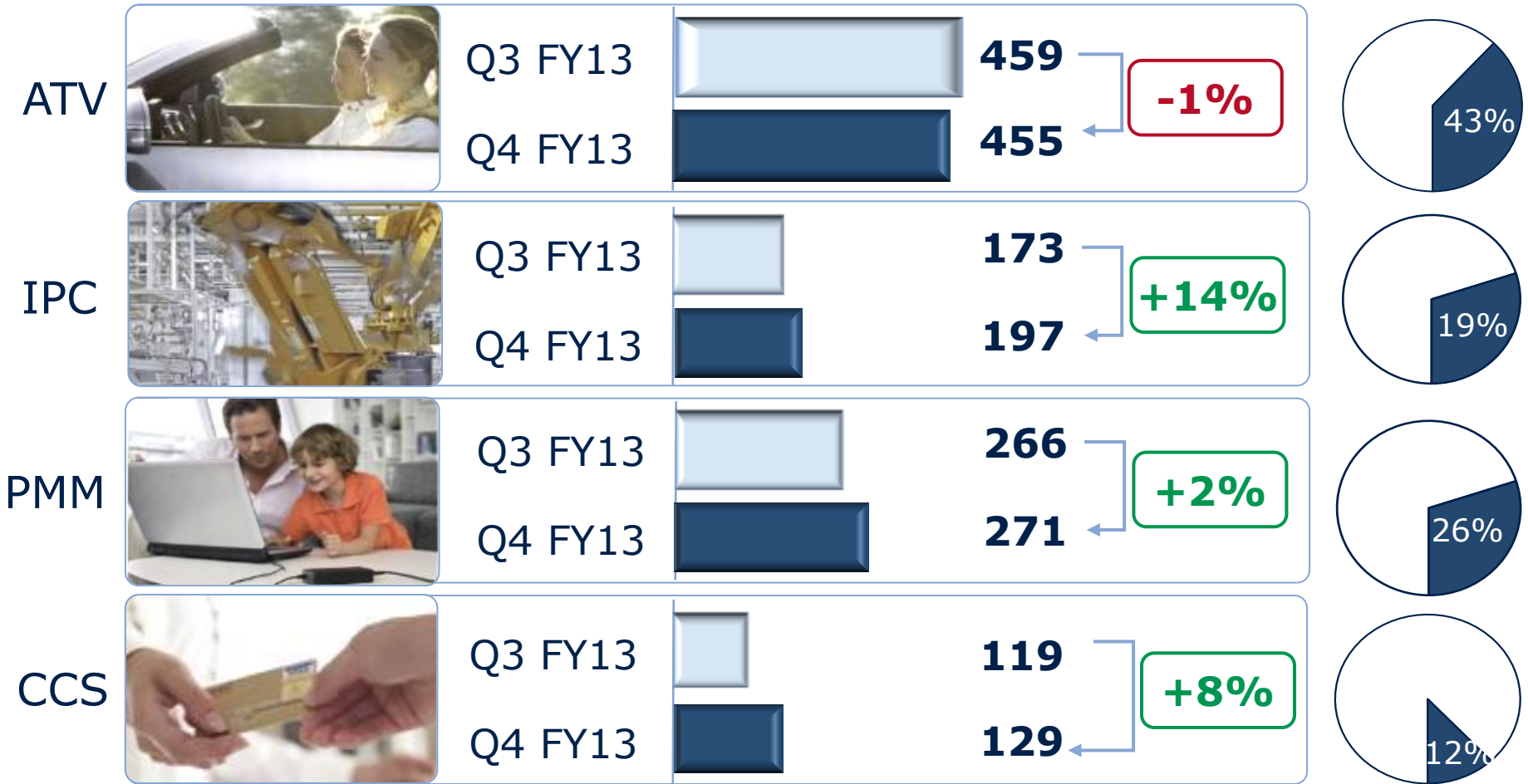
*Total Revenue (Q3 FY13: 1,022m €; Q4 FY13: 1,053m €) includes Other Operating Segment (Q3 FY13: 6m €, Q4 FY13: 5m €), Corporate & Eliminations (Q3 FY13: -1m €, Q4 FY13: -4m €).

Infineon Segment Results
Q4 FY13 vs Q3 FY13

Segment Result* (SR) in € Million		SR Margin

		SR	SR Margin
ATV	Q3 FY13	52	11%
	Q4 FY13	57	13%
IPC	Q3 FY13	13	8%
	Q4 FY13	33	17%
PMM	Q3 FY13	46	17%
	Q4 FY13	49	18%
CCS	Q3 FY13	10	8%
	Q4 FY13	12	9%

*Total Segment Result (Q3 FY13: 117m €; Q4 FY13: 148m €) includes Other Operating Segment (Q3 FY13: -2m €, Q4 FY13: -1m €), Corporate & Eliminations (Q3 FY13: -2m €, Q4 FY13: -2m €).

Revenue Split by Segments

FY 2013 Revenue: € 3,843m

Automotive

IPC

ATV
€ 1,714m

IPC
€ 651m

CCS
€ 463m

PMM
€ 987m

Chip Card
& Security

PMM

OOS+
C&E*
€ 28m

* Other Operating Segments;
Corporate & Eliminations.
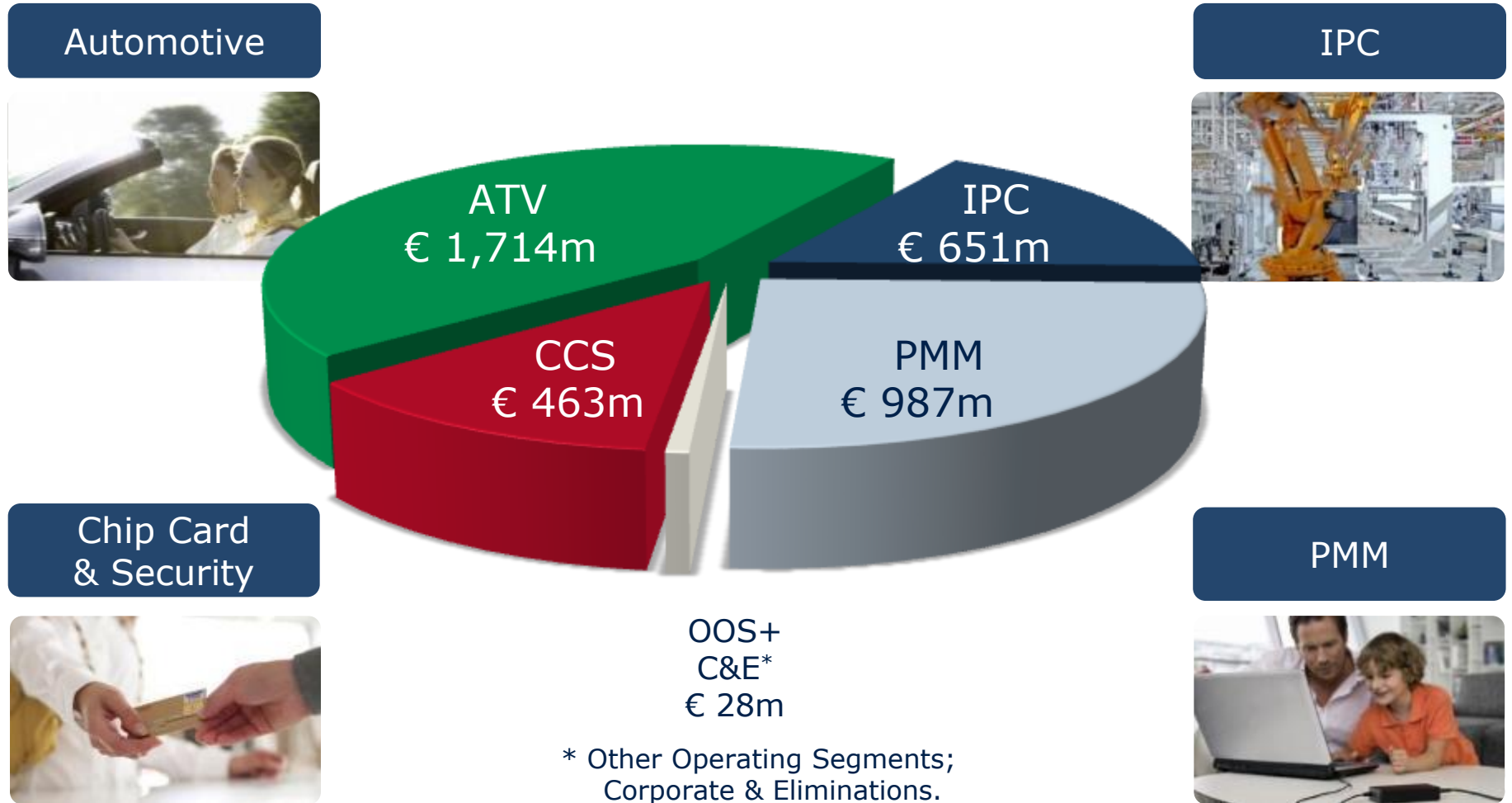
Proportional Revenue Infineon Group by Regions: FY 2013 and FY 2012

Americas
12% 13%

Europe, Middle East, Africa (EMEA)
44% 41%
therein: Germany 23% 21%

Asia / Pacific
38% 40%
therein: China 16% 18%

Japan
6% 6%
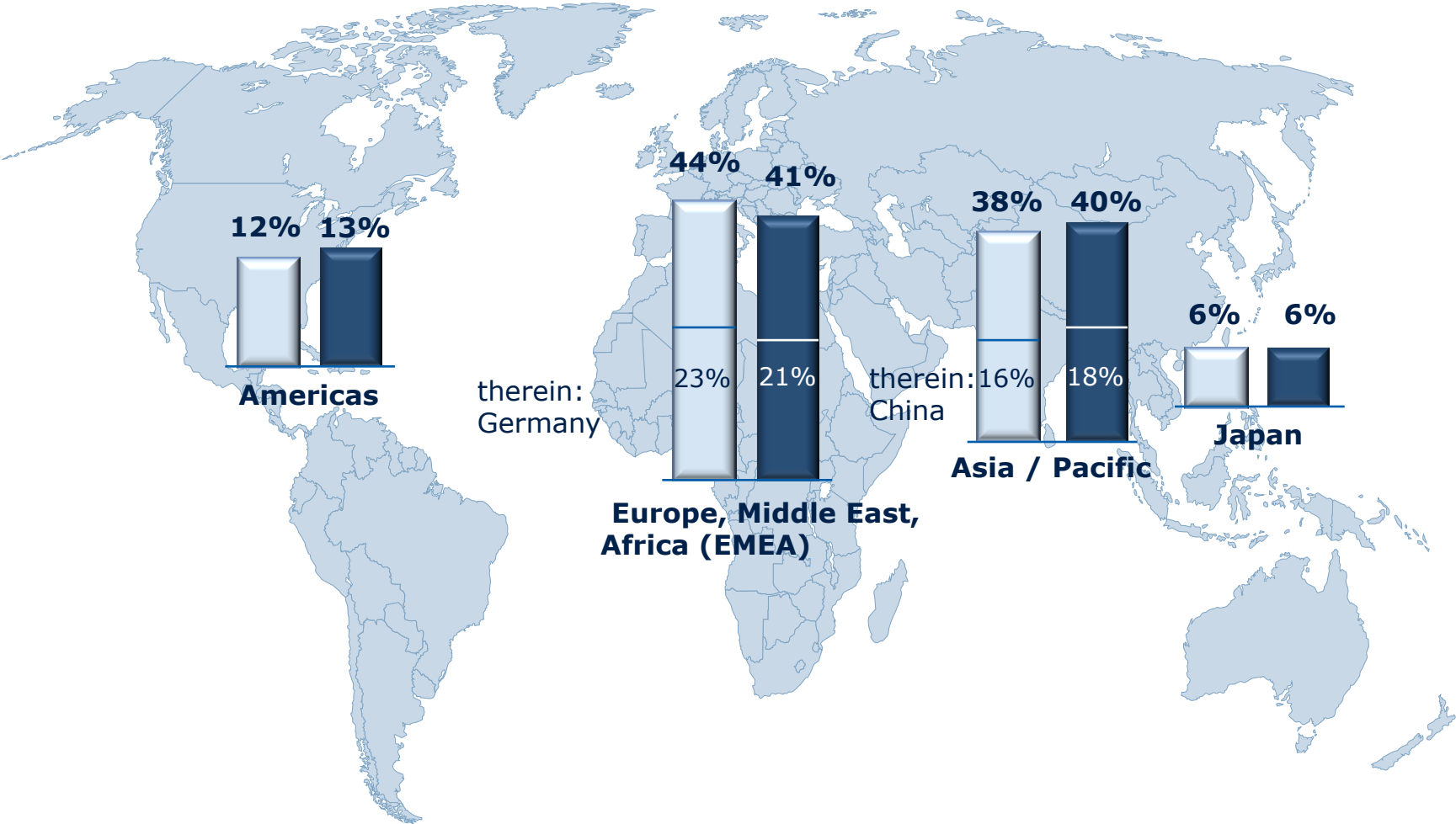
☐ FY 2012 ■ FY 2013

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We Focus on Our Target Markets

Focus Areas

- Energy Efficiency
- Mobility
- Security

Core Competencies

- Analog/Mixed Signal
- Power
- Embedded Control
- Manufacturing Competence

Our Target Markets

- Automotive
- Industrial Electronics
- Information and Communications Technology
- Security

We Focus on Three Areas with Highly Attractive Future Perspectives

Energy Efficiency | Mobility | Security

Automotive

Industrial Power Control

Power Management & Multimarket

Chip Card & Security

Energy Efficiency

Key Trends

- Soaring total energy demand across the globe amid dwindling fossil energy resources

- Strong CO_2 policies to achieve climate goals

- Tapping renewable energies as sustainable energy sources

- Electrification of the drivetrain of commercial and passenger vehicles

Our Contribution

- Infineon delivers semiconductor innovations playing a valuable role in minimizing power loss and maximizing power savings along the entire energy supply chain, extending from generation through distribution to actual consumption.

- Our products are the basis for intelligent and optimal use of energy resources in industrial, computing and consumer applications, and in cars.

Mobility

Key Trends

- Rigid CO_2 regulations and rising oil price

- Increasing rules on safety, focusing on preventive measures

- Rising new requirements in cars for emerging markets

- Urbanization, globalization and demographic change

- Strong investments in local and long distance public transportation systems

Our Contribution

- Leading semiconductor solutions contributing to a more sustainable mobility in terms of reduced fuel consumption/emissions, improved safety and affordability.

- As an innovation driver and supplier of key components for electric and hybrid vehicles, Infineon will actively help to shape the paradigm shift towards electro mobility on the road.

- Innovative public transportation solutions for traction and electronic tickets.

Security

Key Trends

- Secure communication everywhere utilizing mobile phone and internet
- Move to electronic identification of documents and products
- Contactless cards for payment and electronic tickets
- Increased electronics in cars, calling for secure data handling
- Introduction of smart grids calling for advanced data security

Our Contribution

- Tailored security according to system requirements, enabling the implementation of transparent security in everyday systems.

- Leverage our worldwide leadership in security know-how for smart cards in automotive and industrial applications increasingly demanding security.

- Combining both hardware security and cryptography, our products build the basis for privacy and security while maintaining personal freedom and facilitating extended communication capabilities.

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■ Market and Business Development Fourth Quarter FY 2013

■ Business Focus

■ Segments, Products and Technology

■ General Company Information

Tight Customer Relationships are Based on System Know-how and App Understanding

ATV
- Autoliv
- HELLA
- Mitsubishi
- BOSCH
- Continental
- DELPHI
- DENSO
- OMRON
- LEAR CORPORATION
- MAGNETI MARELLI
- HYUNDAI
- TRW
- Valeo

IPC
- ABB
- ALSTOM
- BOMBARDIER
- Danfoss
- Rockwell Automation
- ENERCON ENERGY FOR THE WORLD
- GOLDWIND SCIENCE & TECHNOLOGY
- Schneider Electric
- SEMIKRON innovation+service
- SMA
- SIEMENS
- SUNGROW
- TOSHIBA
- YASKAWA

PMM
- AAC Acoustic Technologies
- DELL
- hp
- DELTA
- GoerTek have sound, will travel
- EMERSON
- ERICSSON TAKING YOU FORWARD
- LITEON
- HUAWEI
- Life's Good LG
- IBM
- OSRAM
- muRata
- Quanta Computer
- SAMSUNG

CCS
- hp
- GD
- gemalto security to be free
- GPO
- OBERTHUR TECHNOLOGIES
- SAFRAN Morpho
- Watchdata

Distributors
- ARROW
- AVNET
- JCET 晶川电子
- RUTRONIK ELECTRONICS WORLDWIDE
- ASC
- TOMEN ELECTRONICS
- wpg

Market-Oriented Business Structure

Segments

Core Applications

Segment	Core Applications
Automotive	Powertrain; Hybrid and electric vehicles; Chassis and comfort electronics; Safety
Industrial Power Control	Renewable energy generation; Energy transmission; Uninterruptable power supplies; Industrial drives; Industrial vehicles; Traction; Home appliances
Power Management & Multimarket	Power supplies for IT and telecom, server, PC, notebook, tablet, smart phones, consumer electronics; Mobile devices (smartphones, tablets, navigation devices); Cellular network infrastructure; Light management incl. LED lighting; Inverter for photovoltaic rooftop systems (< 3kW)
Chip Card & Security	Mobile communication; Payment systems; Near Field Communication (NFC); Electronic passports, ID cards, healthcare cards, driver's licenses; Ticketing, access control; Trusted computing; Authentication

Customers

Product Range

Automotive (ATV)

- Microcontrollers (8-bit, 16-bit, 32-bit)
- Software development platform DAVE™
- Discrete power semiconductors (MOSFETs, IGBTs)
- IGBT modules
- Voltage regulators
- Power ICs
- Bus interface devices (CAN, LIN, FlexRay)
- Magnetic sensors
- Barometric pressure sensors
- Wireless transmit and receive ICs (RF, radar)

Industrial Power Control (IPC)

- IGBT module solutions incl. IGBT stacks
- IGBT modules
- Discrete IGBTs
- "Bare die" business
- Driver ICs

Power Management & Multimarket (PMM)

- Discrete high-voltage power transistors
- Discrete low-voltage power transistors
- Driver ICs
- Control ICs
- RF power transistors
- Small-signal components
- CMOS RF switches for antenna modules
- MEMS and ASICs for silicon microphones
- Customized chips (ASICs)

Chip Card & Security (CCS)

- Contact-based security controller
- Contactless security controller
- Dual-interface security controller (contact-based and contactless)

New Era:
Driving Demand for Power Semiconductors

'90 – '10	'10 – '30	Changes

Courtesy: Tesla

- Electrification in cars with Internal Combustion Engine as well as the trend towards emobility drives the demand for power semiconductors.

- Shift towards renewable energies requires significantly more high-power semiconductors per MW of power generated.

Courtesy: Facebook

- Higher efficiency in power conversion lowers CO_2 and total cost of ownership.

- Stronger demand for goods containing power semiconductors due to increasing standard of living in BRIC countries.

Automotive Overview

Product Range

- **Sensors**: pressure, magnetic, wireless control ICs, radar
- **Microcontrollers**: 8-bit, 16-bit, 32-bit
- **Power**: MOSFETs, IGBTs, smart power ICs: voltage regulators, bridges, driver ICs, CAN / LIN / FlexRay™ transceiver*, DC-DC converters, power system ICs, system-on chip, embedded power ICs
- **Hybrid & Electric Vehicle**: HybridPACK™ modules, Automotive Easy modules, gate driver ICs, MOSFETs, IGBTs

Core Competencies/ Value Proposition

- **Automotive commitment**: More than **40 years** of automotive **system and application expertise**
- **Complete** automotive **system provider**
- **Hybrid and Electro mobility:** industry **leading expertise** and product portfolio
- **Functional Safety (ISO26262)** and **Security** enabling car solutions
- **Worldwide** development, production and support sites for automotive semiconductors
- **Next Level of Zero Defect**: most comprehensive quality program of the industry

Market Positions

- **No. 2** in Automotive semiconductors worldwide
- **No. 1** Europe
- **No. 2** North America
- **No. 1** APAC & Others**
- **No. 5** Japan

Source: Strategy Analytics (April 2013)

We Focus on Future Business
Making Cars Clean

Market Trends

- Dwindling energy resources
- Urbanization
- Stricter CO_2 emission legislations
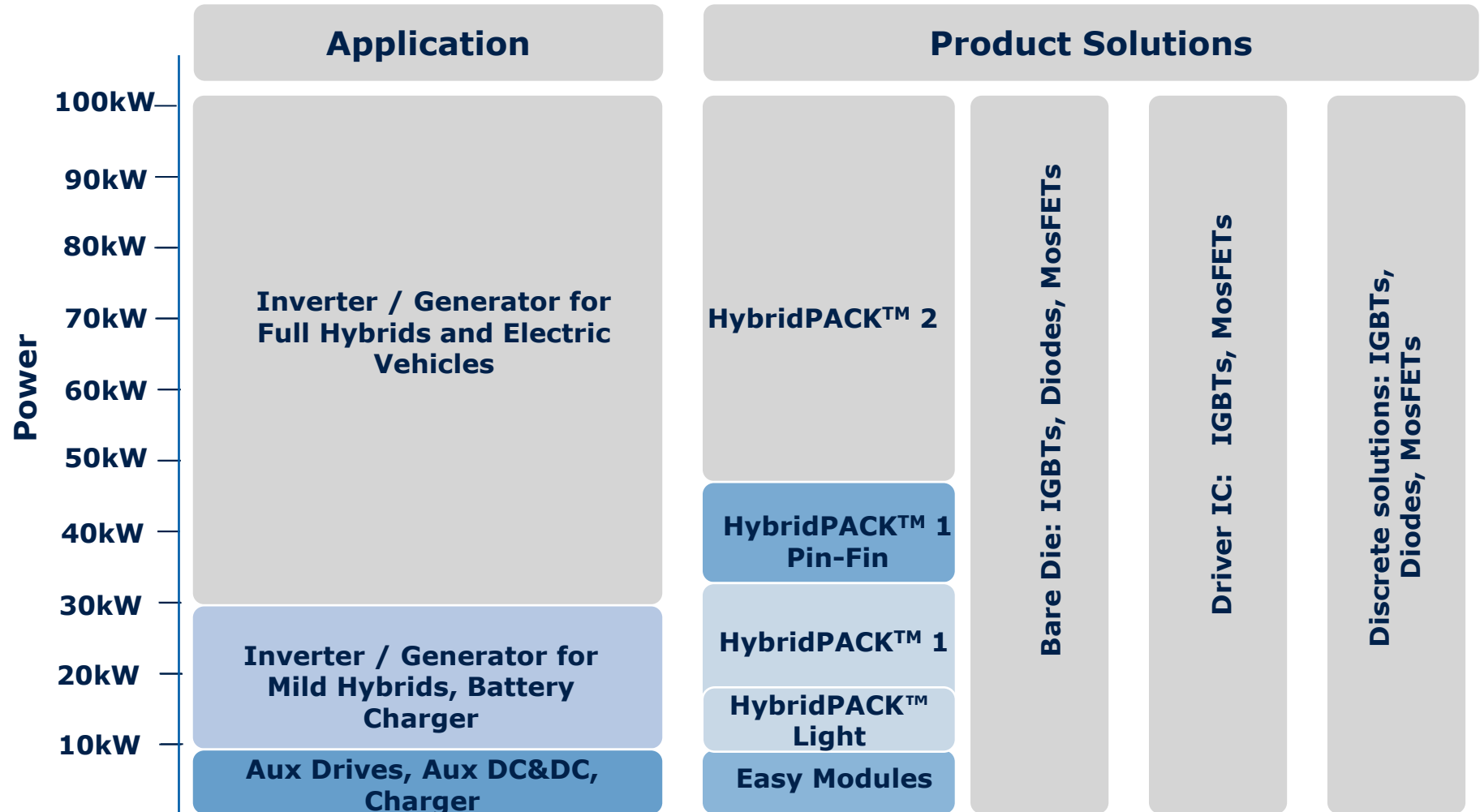- Growing environmental awareness

Infineon's Opportunities

- Infineon components are key for CO_2 reduction: total improvement of CO_2 emission ~23 g/km.

- We offer Hybrid and electric drivetrain products (HybridPACK™).

- No electric vehicle without semiconductors: electric drive and control, battery management, on-board battery charging and power grid communication.

Note: Baseline CO_2 reduction in g/km: 170 g/km on Ø EU cars

Target Applications for Electric Drive Train Product Portfolio

Application	Product Solutions

Power

Power	Application	HybridPACK™	Bare Die: IGBTs, Diodes, MosFETs	Driver IC: IGBTs, MosFETs	Discrete solutions: IGBTs, Diodes, MosFETs
100kW					
90kW		HybridPACK™ 2			
80kW	Inverter / Generator for Full Hybrids and Electric Vehicles				
70kW					
60kW					
50kW					
40kW		HybridPACK™ 1 Pin-Fin			
30kW	Inverter / Generator for Mild Hybrids, Battery Charger	HybridPACK™ 1			
20kW		HybridPACK™ Light			
10kW	Aux Drives, Aux DC&DC, Charger	Easy Modules			

BMW and Infineon: Working together to shape the future of electro mobility

Power module

- 75 semiconductors ensure a highly efficient electric drive in the BMW i3, e.g. Microcontroller AUDO Future, IGBT Power Module HybridPACK™ 2, EiceDRIVER™ Products, CoolMOS™ High voltage MOSFETs.

- Further components: airbag control, LED light modules, steering locks, windshield wipers and seatbelt retractors.

Industrial Power Control Overview

Product Range

- IGBT modules and stack assemblies
- IGBT chips and discretes
- Driver ICs and Driver Boards (EiceDRIVER™)

Core Competencies/ Value Proposition

- High quality products and services
- Leading edge technology and IP portfolio
- System expertise with broad application competence
- Strong worldwide presence with local sales and application support
- Dedicated account teams and distributors

Market Positions

- No.1 in Bipolar High Power Thyristor/Rectifier with 24.8% market share*
- No. 2 in Power Modules with 18.4% market share.
- No.1 in Discrete IGBT Semiconductors with 23.7% market Share

* This business is part of the Infineon Technologies Bipolar GmbH & Co. KG, a Joint Venture with Siemens.

Source: IMS Research, August 2012

Power Components for Drive Control of Train Systems

High-Speed Trains

Metro Trains

Infineon Parts

- Power: 5 to 10MW per train
- 80 to 120 IGBT modules per train
- Semiconductor content: ~EUR 100,000 per train

- Power: 0.5 to 1MW per train
- 25 to 50 IGBT modules per train
- Semiconductor content: ~EUR 10,000 per train

Power Management & Multimarket Overview

Product Range

- Power Discretes and Driver ICs
- Power ICs, Digital Power Management
- LED Drivers
- RF Diodes and Transistors, RF Power
- Chips for Silicon MEMS Microphones, TVS Diodes
- ASIC design solutions for authentication and battery management

Core Competencies/ Value Proposition

- Technology Leadership in Power & RF:
  - Energy Efficiency
  - Power Density, system size and weight reduction
  - Connectivity and reliable, clean Data Transmission for 50bn devices in 2020
- Revolutionary Innovation made "easy to use"
  - Application centric Innovation
  - Integration competence: Power/RF, Digital Power, Discretes, chip embedding

Market Positions

- No. 1 in Power Discretes
  (IHS: The World Market for Power Semiconductor Discretes & Modules – 2013, Sept 2013)
- No. 2 in Discrete MOSFETs
  (IHS: The World Market for Power Semiconductor Discretes & Modules – 2013, Sept 2013)
- No. 2 in Silicon for MEMS Microphones
  (IHS: MEMS Microphones go Mainstream, 2012)
- No. 3 in RF Power Devices
  (ABI Research: RF Power Amplifiers; Dez 2012))

Power Components for Servers and RF Devices for Cellular Infrastructure

Energy Efficient Server

Cellular Infrastructure

Infineon Components

- Efficiency values of 95% and higher
- Technology leadership in silicium and silicumcarbide products
- Highest power density enabling best cost-performance ratios
- Unique system solutions with MOSFETs, power ICs and driver products

- Applicable for all standard frequencies of 2G, 3G, 4G (450 MHz to 2.7 GHz)
- Industry leading power efficiency for LTE
- Wide range of devices with power levels from 4 – 700 W
- Best-in-class thermal performance

Social Networks and Cloud Computing Driving Demand for Highest Efficient Power Supplies

Digital Power Management (DPM) Gaining Traction in Server Market

amazon.com.

Google

f

Picasa

t

Microsoft®

You Tube

- Globally, we see one new data center per week with up to 100 MW of power consumption.
- Efficiency of power supply (AC/DC, DC/DC) of utmost importance.
- DPM best solution for flexible load dynamics.
- Change in value chain: servers no longer from the shelf but designed by ODMs according to specification of data center operator.

CoolMOS™ **OptiMOS™** **Driver IC**

- DPM opens the door for bundling with other products.
- Recent design win: Infineon offers DPM controllers along with driver ICs and MOSFETs to Taiwanese ODM.

Chip Card & Security Overview

Product range

- Contactless and contact-based security products for Communication, Payment, Government ID, Transport, Access, Object ID, Entertainment and Platform Security

- Extensive packaging and service portfolio

- Innovative solutions from basic security RFID and memories to high-end security controllers (including the award winning SLE 78 family)

Core competencies/ Value proposition

- Tailored security: right level of security at the best cost-performance ratio

- Contactless excellence: focus on interoperability and dual interface

- Embedded control: right trade-off between computing power, power consumption, level of security and cost

Market positions

- No. 1 in the Microcontroller Smart Card IC market with 24%[1] market share in 2012 by revenue
- Market leader in Payment[2] with 33% market share in 2012 in terms of volume
- Market leader in Gov ID. Only IC provider shipping to the ePass projects of the world's five biggest countries. Providing chips for more than 70% of National eID projects in Europe
- Market leader in TPM and PayTV

Source: [1]IMS Research, Sept 2013; [2]IMS, Aug 2013; [3]IMS, March 2013

Security Chips for Taiwan's Electronic Passport Program

"Integrity Guard" is the preferred solution for electronic passports and IDs

- Infineon is the **only supplier** and has started shipping security chips of the SLE78 product family based on the digital security technology "**Integrity Guard**".

- Taiwan has been issuing **one million electronic passports (ePassports) per year** to its approximately **23 million citizens** since 2008. The passports have a validity of ten years and comply with latest ICAO (International Civil Aviation Organization) standards for travel documents.

- This is the **second major project** driven by the government of Taiwan that relies on security chips from Infineon: **more than 25 million pieces** have already been shipped for the **electronic health cards of the Taiwan Health Care Project**.

ID cards, passports, health cards and driving licenses increasingly are being issued in the form of **electronic documents**, comprising a security chip, in order to protect them more effectively against counterfeiting and falsification while increasing convenience for the ID holder.

Chips for the World's First ePassports of the Newest Generation

Kosovo's ePassports incorporate the Supplemental Access Control (SAC) protocol

- Infineon supplies security chips of the SLE 78 product family with "**Integrity Guard**," which offers the highest level of data security over the long term and are **ideally suited for sovereign documents with a long period of validity**.

- Kosovo's are the **world's first electronic passports** incorporating **the Supplemental Access Control (SAC) protocol**, which enhances protection against unauthorized access and possible abuse of personal data.

- In contrast to the earlier generation BAC (Basic Access Control) protocol, **SAC is based on asymmetric encryption**.

- As the first European country to comply with the new requirement, the **Republic of Kosovo will issue 800,000 electronic passports**.

- **Within the EU, SAC will be mandatory** for ePassports issued **from December 2014**.

According to current estimates from market research firm IHS, roughly **192 million electronic passports** are in circulation **in Europe**. In this region, **over 30 million new electronic passports are issued each year**.

Advancing Trusted Computing with New OPTIGA™ TPM Family

Security Chips serve Industrial/Embedded Environments and Support Next Generation TPM 2.0 Firmware

- Infineon introduced a **new family of Trusted Platform Modules (TPM)** that broaden the application base for trusted computing and mark the first availability of discrete security chips **supporting the next generation TPM 2.0 specification**.

- With extended temperature range versions, support for either serial or parallel device interfaces and ability to run either TPM 1.2 or 2.0, **Infineon's OPTIGA™ TPMs** support **current and anticipated future requirements for hardware-based trusted system applications** across industrial, embedded, mobile or tablet and traditional computing environments.

- Infineon's TPM security chips have received **TCG certification** based on the international security standard "**Common Criteria**" and on TCG's own compliance tests.


"With launch of the new OPTIGA™ TPM family, Infineon supports both the evolution to higher security implementation with TPM 2.0 and the growing demand for Trusted Computing functionality in computing systems," *said Juergen Spaenkuch, Vice President and General Manager Platform Security*

Semiconductor Technology Portfolio

Technology portfolio fits needs of logic and power applications

Power/Analog
incl. Green Robust
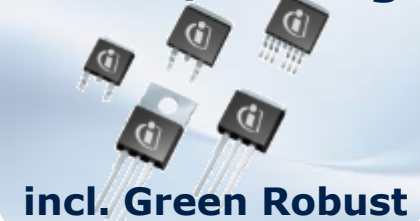
Analog Bipolar: DOPL, Ax, BIPEP, B4C	**DMOS:** Low Voltage Trench MOSFET (OptiMOS™)
Analog BiCMOS: B6CA, B6CA-CT, B7CA, SPT170 500 - 350nm HV-CMOS-SOI	**HV-DMOS:** Superjunction MOSFET (CoolMOS™)
Smart Power: 1200-130nm BIP/CMOS/DMOS SPTx (Automotive, EDP) (BCD)	**IGBT:** Trench IGBT 600-6500V, rev. cond., fast recov. Diodes
Smart: CMOS/DMOS, SMARTx, (SmartMOS) MSMARTx, SSMARTx, Opto-TRIAC	**SiC:** Diode, JFET

all of them adopted for automotive and industrial requirements

MEMS/Sensors

Analog ICs: B6CA, B7CA Coreless Transformer	**Pressure:** BxCSP, TIREPx
Magnetic: BxCAS, C9FLRN_GMR	**Silicon-Microphones:** DSOUND
Opto: OP-DI, OP-TR, OP-C9N, µ-modules	

CMOS

Digital CMOS: 800nm – 65nmTechnology Nodes (Platform <180nm incl. RF, AMS)
Analog/Mixed Signal: 500nm – 180nm Technology Nodes (CxNA)
eNVM: EEPROM: IMEMR, C9FL, OTP: C5OP (Automotive)
eFlash/EEPROM: 250nm – 65nm CxFL (Chip Card), CxFLA, CxFLN (Automotive)
HV-CMOS: 130nm, C11HV

RF/Bipolar

RF BiCMOS: 25GHz – 100GHz: B6HFC, B9COPT, B10C
Bipolar IC: 2GHz…200GHz RF-Bipolar: BxHF   **SiGe**: B7HFM, B7HF_SLC, B7HF200
HiPAC: Al/Cu Integrated Passives   **RF Switches**: C7NP, C11NP
P7Mxx, P7Dxx, P8Mxx
Bipolar/Discretes/MMIC:
RF-Transistors   NF-TR; BxHF(D/M),   **SiGe**: B7HFD/M, B7HF_SD
Power Amplifier: LDMOS, LDxM, LDxIC, LD9AB   **RFMOS**: HFM
Diodes: NF-DI, Tuner: DxT, Schottky: DxS   **PIN**: DxP

Package Technology Portfolio

IC

Wafer Level Packages, Bare Die	Laminate based Packages	Leadframe based Packages	Chip Card
Surface Mount Technology (SMD) **Wafer Level** w/o redistribution ▪ WLP (fan-in) w/redistribution ▪ WLB (fan-in) ▪ eWLB (fan-out) ▪ Blade **Bare Die** ▪Wirebond ▪Flip chip	**SMD** ▪ OCCN [1,2] ▪ BGA ▪ LBGA ▪ xFBGA, xFSGA	**Through Hole** ▪ DIP [2] **SMD** ▪ PLCC [2] ▪ TSSOP ▪ TQFP ▪ LQFP ▪ MQFP **Leadless** ▪ VQFN ▪ WQFN ▪ O-LQFN [1] ▪ XSON ▪ USON	**Mold on LF** ▪ P-MCCx **Mold** ▪ P-Mx.x **Chip on Flex** ▪ FTM **UV Globe top** ▪ T-Mx.x **PRELAM** ▪ PPxx **Flip Chip** ▪ S-MFCx.x **Wafer** ▪ Bumped ▪ Diced

Power

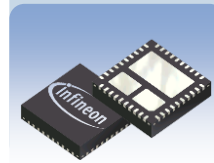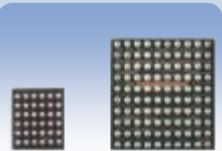| Discretes	Sensors	High Power	Power
SMD leaded ▪ SOT ▪ SOD ▪ TSOP ▪ TSSOP **Flat lead** ▪ TSFP ▪ SC **Leadless** ▪ TSLP ▪ TSSLP ▪ TSNP **Wafer level** ▪ WLP ▪ WLL	**Through Hole** ▪ PSSO **SMD Leaded** ▪ DSOSP **Open cavity** ▪ DSOF	**Power Modules** ▪ Easy ▪ 34mm ▪ 62mm ▪ Econo ▪ Econo-PACK™+ ▪ Prime-PACK™ ▪ IHM ▪ IHV ▪ Hybrid-PACK™	**Through Hole** ▪ TO, DIP **SMD** ▪ TO ▪ DSO ▪ SSOP **Leadless** ▪ TDSON ▪ TSDSON ▪ CanPAK™ ▪ TISON ▪ WISON ▪ IQFN ▪ HSOF

1) for specialities only   2) phase-out

Recent Awards: Automotive

Pinnacle Award for Technology (September 2013)

Honoring Infineon for its innovation, which provides *"Delphi with significant competitive advantage"*, and the *"excellent customer service. Infineon is the first semiconductor supplier ever to receive the technology award*."

Innovation Award 2012 (June 2013)

"Infineon was honored with the special "Innovation Award", which was presented by Continental for the first time. This is the fourth time in a row, that Infineon has won a Continental Supplier Performance Award."

Technical Development Award 2011 (July 30, 2012)

"Denso presents its awards to its best suppliers for quality, pricing, technical development, and global collaboration. Infineon is the first non-Japanese component supplier to receive a Denso Technology Development Award."

Excellent Quality Award 2011 (May 30, 2012)

"Toyota Motor Corporation's Hirose Plant has awarded Infineon its Excellent Quality Award for delivering outstanding product quality during 2011."

Recent Awards: Industrial Power Control and Power Management & Multimarket

Bombardier Sustainability Award (July 9, 2013)

"Bombardier Transportation has presented Infineon Technologies AG with its Supplier Sustainability Award 2013. Infineon won the prize for reaching the sustainability goals it had set itself. The Jury deemed Infineon's high level of product responsibility as well as the positive environmental effects its assortment has meant for the sustainable mobility of Bombardier Transportation particularly worthy of a prize."

Elektronik Product of the year award (March 19, 2013)

"Infineon's product family JFETs CoolSiC™ was honored with the Product of the year award in the category automatization from Elektronik. The revolutionary CoolSiC™ SiC JFET family represents Infineon's leading edge solution to bring actual designs towards new and so far unattainable efficiency levels."

Preferred Supplier Award 2013 (Nov 11, 2012)

"On the Global Suppliers Day of Schneider Electric Infineon was selected as "Preferred Supplier" 2013. Infineon fulfills the certain expectation about the Quality, in time delivery and demonstrated as excellent and open minded business partner. This award was evaluated from more than 100 suppliers worldwide."

Recent Awards: Chip Card & Security

German Prize for IT Security (November 29, 2012)

"Infineon's research project "Cryptographic Protocol with Inherent Side-Channel Resistance" was honored with the 1st prize. The innovative encryption scheme offers data security for price-sensitive mass market products e.g. electronic ski passes, library cards or public transport."

Sesames Award 2012 (November 6, 2012)

"Infineon has been awarded the chip card industry's Sesames Award 2012 for the most innovative product in the category Transportation. The SOLID FLASH™-based SLS 32TLC security controller from Infineon is the industry's first solution that supports conventional public transportation implementations as well as CIPURSE™, the newly defined open standard for the transport industry."

Nomination for the Federal President`s Award for Innovation and Technology (September 12, 2012)

""Integrity Guard" digital security technology has been nominated for the "Deutscher Zukunftspreis 2012". Infineon developed this new generation security technology for applications that require the highest level of data security and long time resilience."

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■ Market and Business Development Fourth Quarter FY 2013

■ Business Focus

■ Segments, Products and Technology

■ General Company Information

Decisive Competitive Advantage: Quality at Infineon

Our aspiration
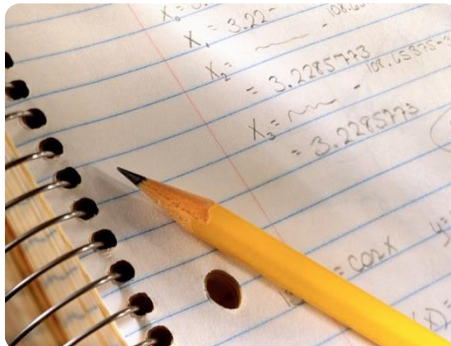
- Preferred partner for our customers
- Smooth production and delivery
- We focus on stability and the 100 percent fulfillment of our commitments

Our path

- Integrated approach along the entire value chain
- Proactive Quality Management for products and processes

Our standards

- International Standards, e.g. TS16949, ISO 9001, IEC 17025
- Specific customer requirements

26,725 Employees Worldwide

USA
499 employees

172	East Coast
327	West Coast

Europe
12,587 employees

71	Great Britain
3058	Austria
8520	Germany
90	Portugal
35	France
97	Italy
184	Romania
23	Sweden
502	Hungary
7	Other Europe

Asia/Pacific
13,639 employees

1831	Singapore
1918	Indonesia
234	India
7709	Malaysia
1615	China*
122	Japan
89	Korea
112	Taiwan
9	Australia

*) incl. Hong Kong

R&D Network in Europe

Warstein

Duisburg

Bristol

Augsburg

Munich, Neubiberg

Padua

Regensburg

Dresden

Linz

Graz

Bucharest

Villach

Worldwide R&D Network (Excluding Europe)

Beijing

Seoul

Shanghai

Morgan Hill

Torrance

Singapore

Malacca

Bangalore

Kulim
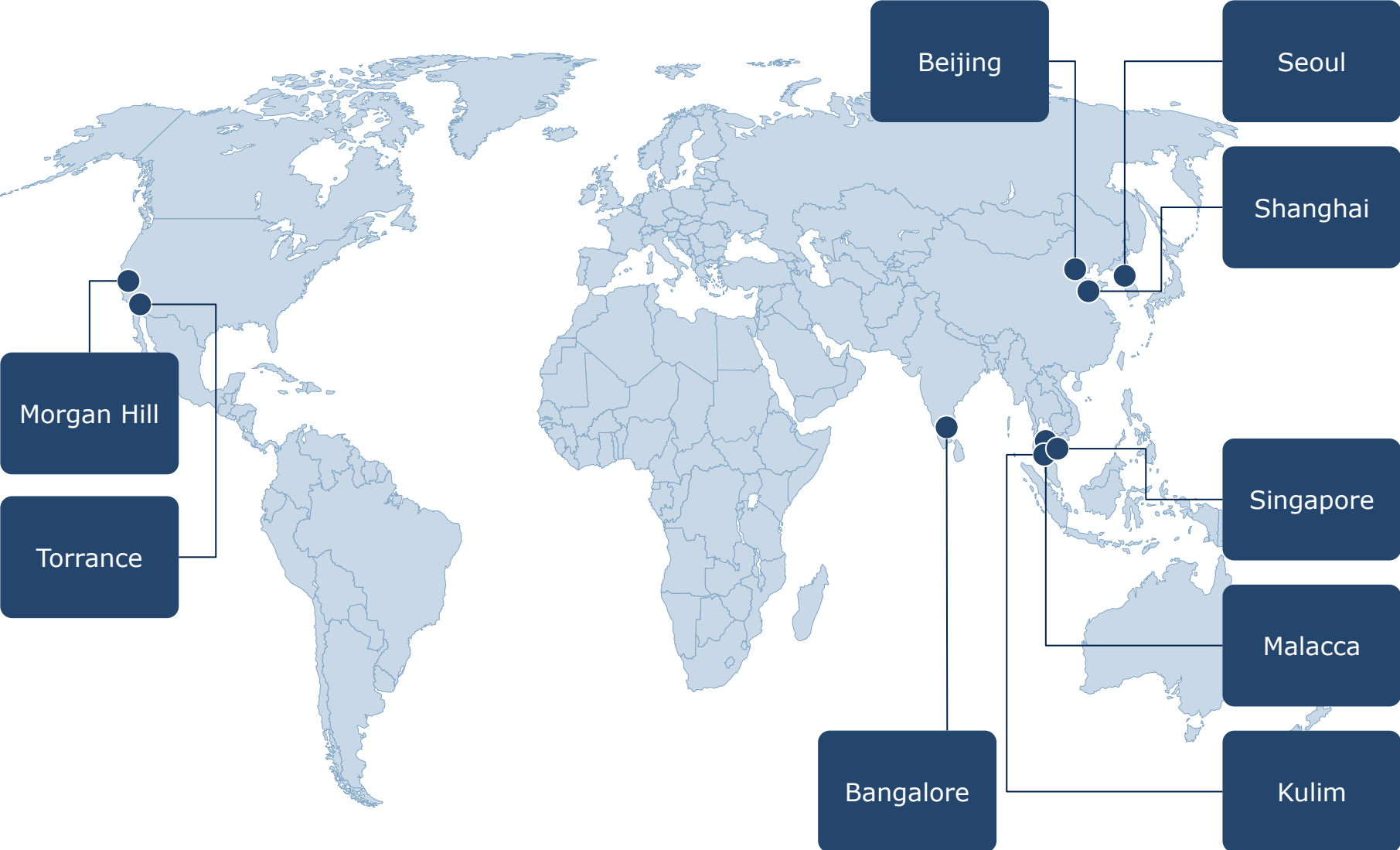
Worldwide Manufacturing Sites
Frontend and Backend

Morgan Hill

Dresden

Kulim

Beijing

Wuxi

Warstein

Singapore

Regensburg

Villach

Cegléd

Malacca

Batam

● Frontend ● Backend

Sales Offices in Europe
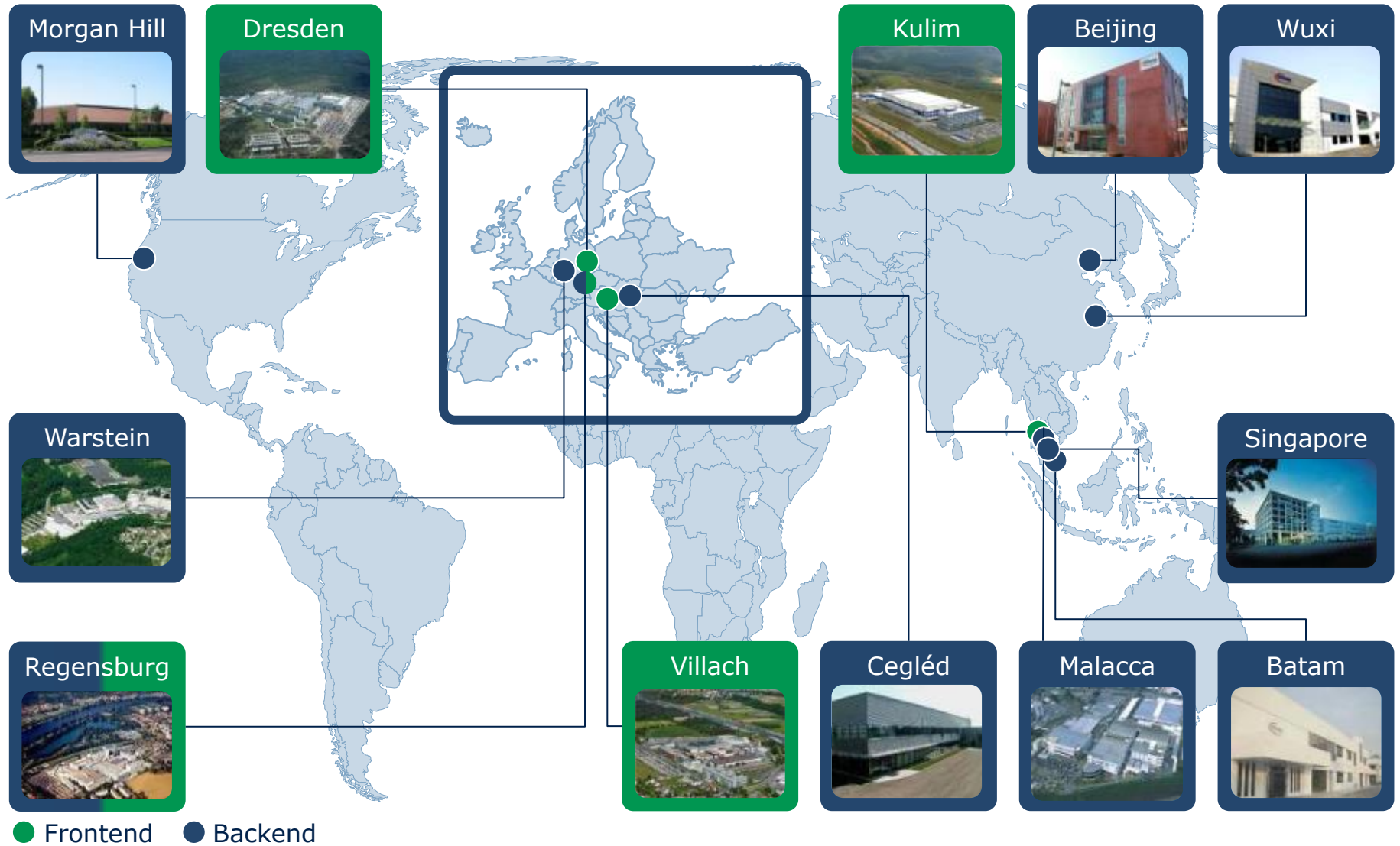
Rotterdam
Duisburg
Warstein
Hanover
Stockholm, Kista
Moscow
Erlangen
Munich, Neubiberg
Bristol
Dublin
Vienna
Groß-ostheim
Zurich
Nuremberg
Milan
Stuttgart, Ditzingen
Saint Denis
Madrid
Toulouse
Marseille
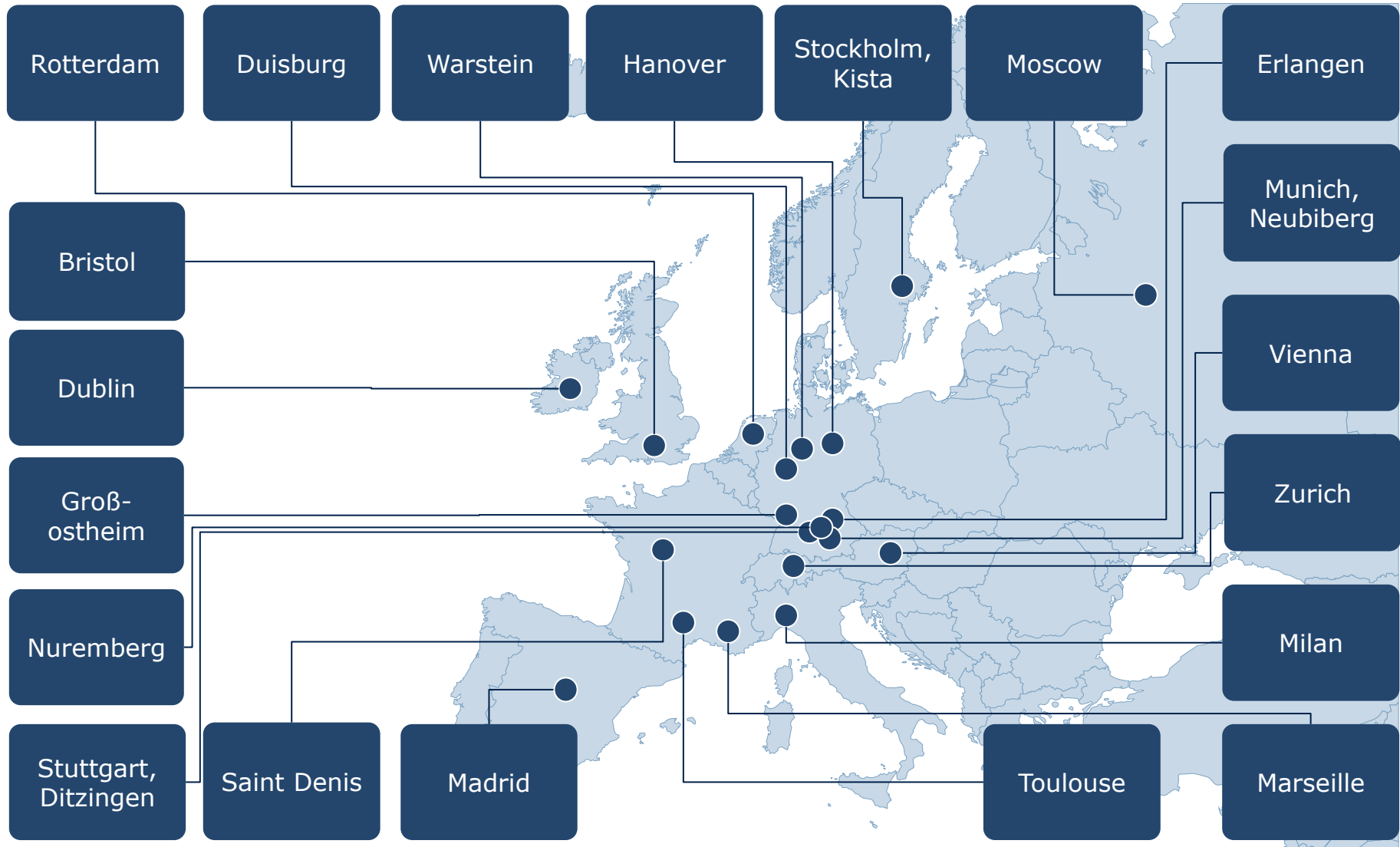
Sales Offices Worldwide (Excluding Europe)

Lebanon

Livonia

Bangalore

Seoul

Wuxi

Hong Kong

Shenzhen

Hayward

Tokyo

Milpitas

Nagoya

Kokomo

Singapore

Osaka

São Paulo

Taipei

Melbourne,
Blackburn

Corporate Social Responsibility
Our Commitment
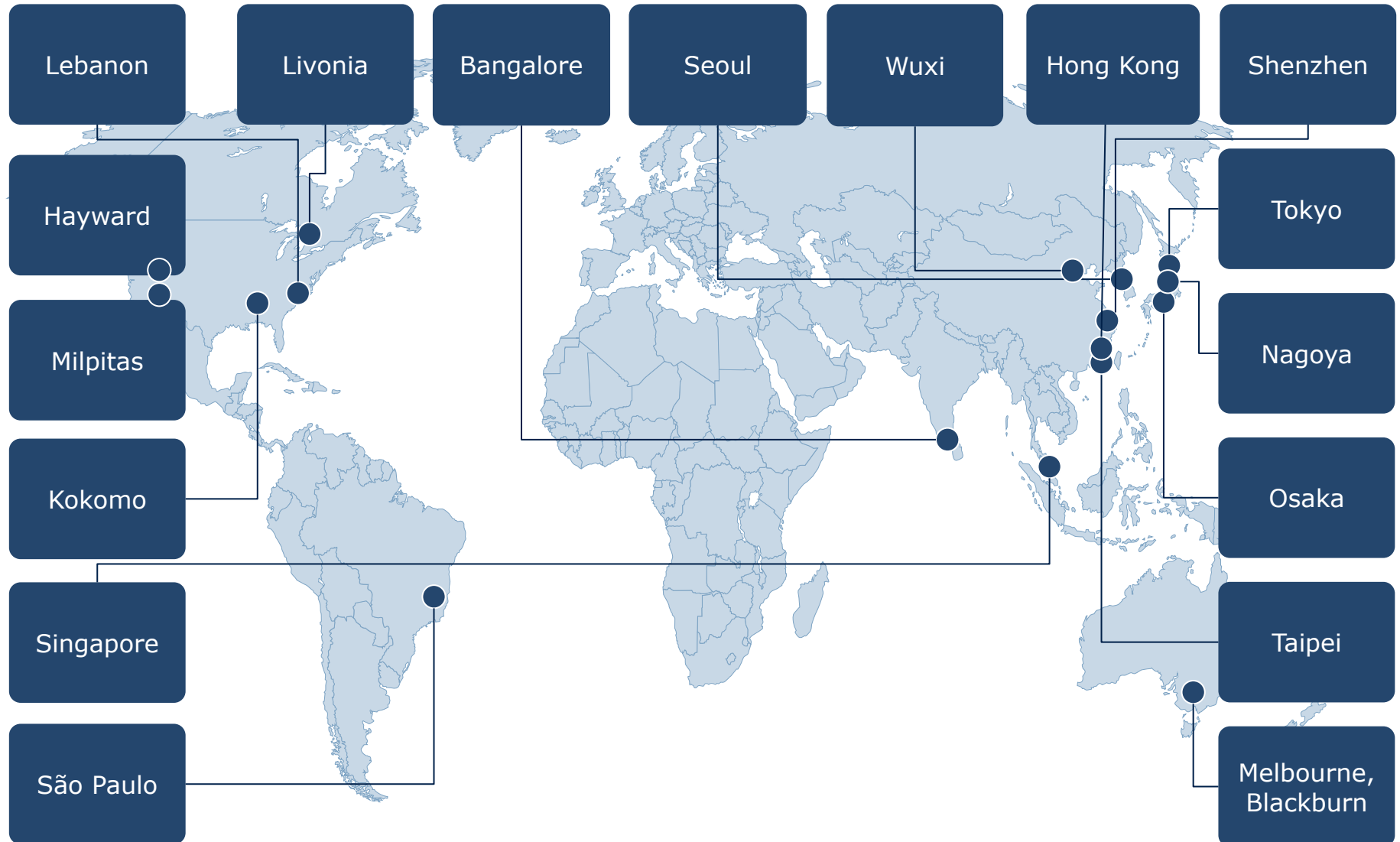
United Nations Global Compact
10 Principles

Human Rights

Principle 1:   support and respect the protection of internationally proclaimed human rights

Principle 2:   make sure they are not complicit in human rights abuses

Labor

Principle 3:   uphold the freedom of association and the effective recognition of the right to collective bargaining

Principle 4:   uphold the elimination of all forms of forced and compulsory labor

Principle 5:   uphold the effective abolition of child labor

Principle 6:   uphold the elimination of discrimination in respect of employment and occupation

Environment

Principle 7:   support a precautionary approach to environmental challenges

Principle 8:   undertake initiatives to promote greater environmental responsibility

Principle 9:   encourage the development and diffusion of environmentally friendly technologies

Anti-Corruption

Principle 10:   work against corruption in all its forms, including extortion and bribery

# Corporate Social Responsibility
Our Understanding

CSR at Infineon comprises our voluntary commitment and contributions in the areas:

Corporate Social Responsibility
Successful CSR Approach

since 2001

FTSE4Good

FTSE4 Good Index

since 2004

UN Global Compact

since 2005

Infineon IMPRES

(Infineon Integrated Management Program for Environment, Safety & Health)

since 2010

Dow Jones Sustainability Index

since 2011

Sustainability Yearbook

since 2012

Energy Management System, integrated in IMPRES

2013

Corporate Responsibility Prime

rated by

oekom research

oekom classification as „Prime"

Continuous CSR Approach

● **Company Foundation**
Worldwide certified environmental management system according to ISO 14001

■ According to RobecoSAM, Infineon is among the top 15% most sustainable companies worldwide and therefore listed in the Sustainability Yearbook

■ RobecoSAM „Runners-up" Award (2013)

ROBECOSAM
Sustainability Investing

MEMBER OF
Dow Jones
Sustainability Indices
In Collaboration with RobecoSAM

Corporate Social Responsibility
Environmental Sustainability
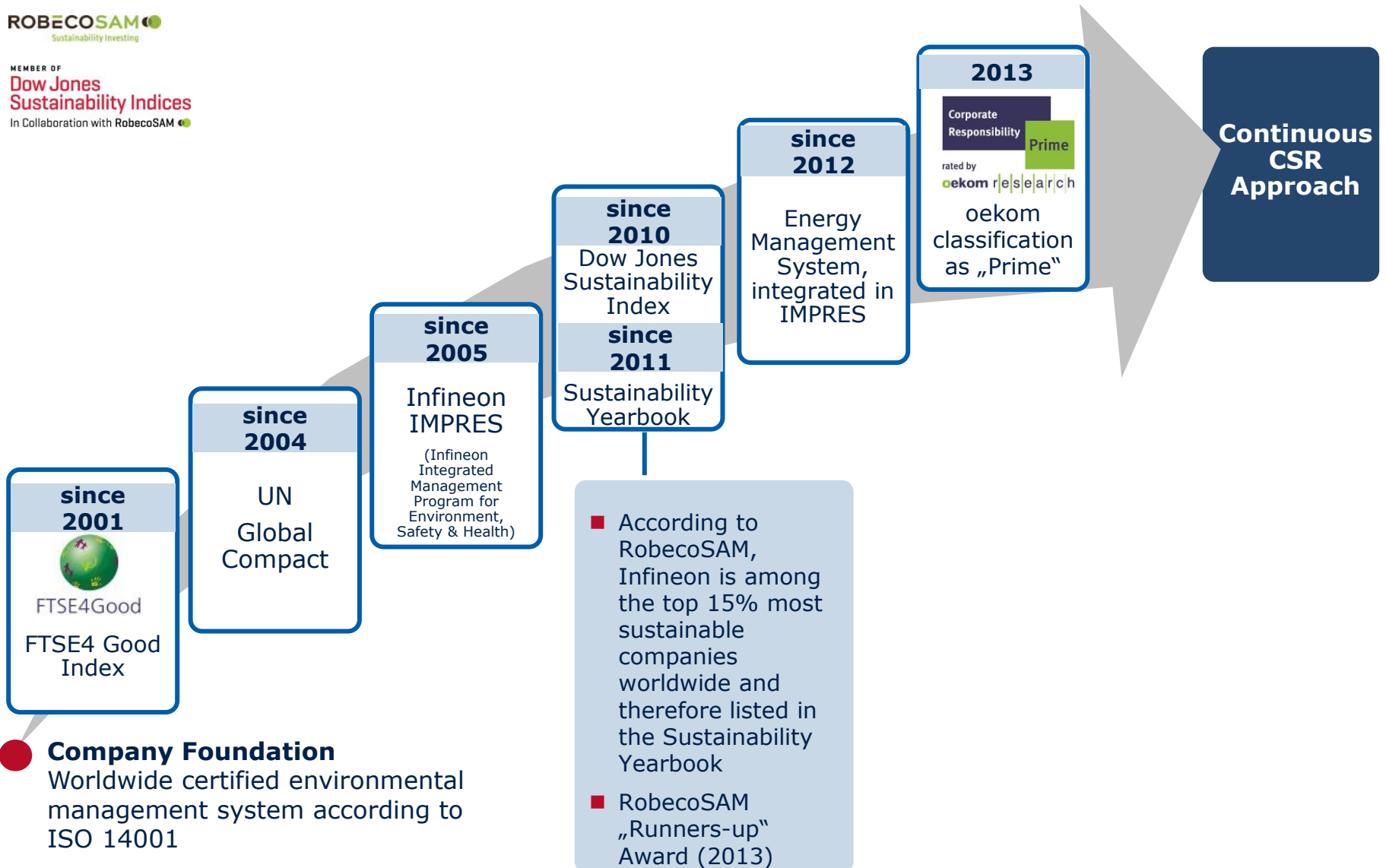
Certifications

Based on our efforts for resources management, safety and health standards, Infineon received the EN ISO 14001, OHSAS 18001 and ISO 50001* multi-site certification.
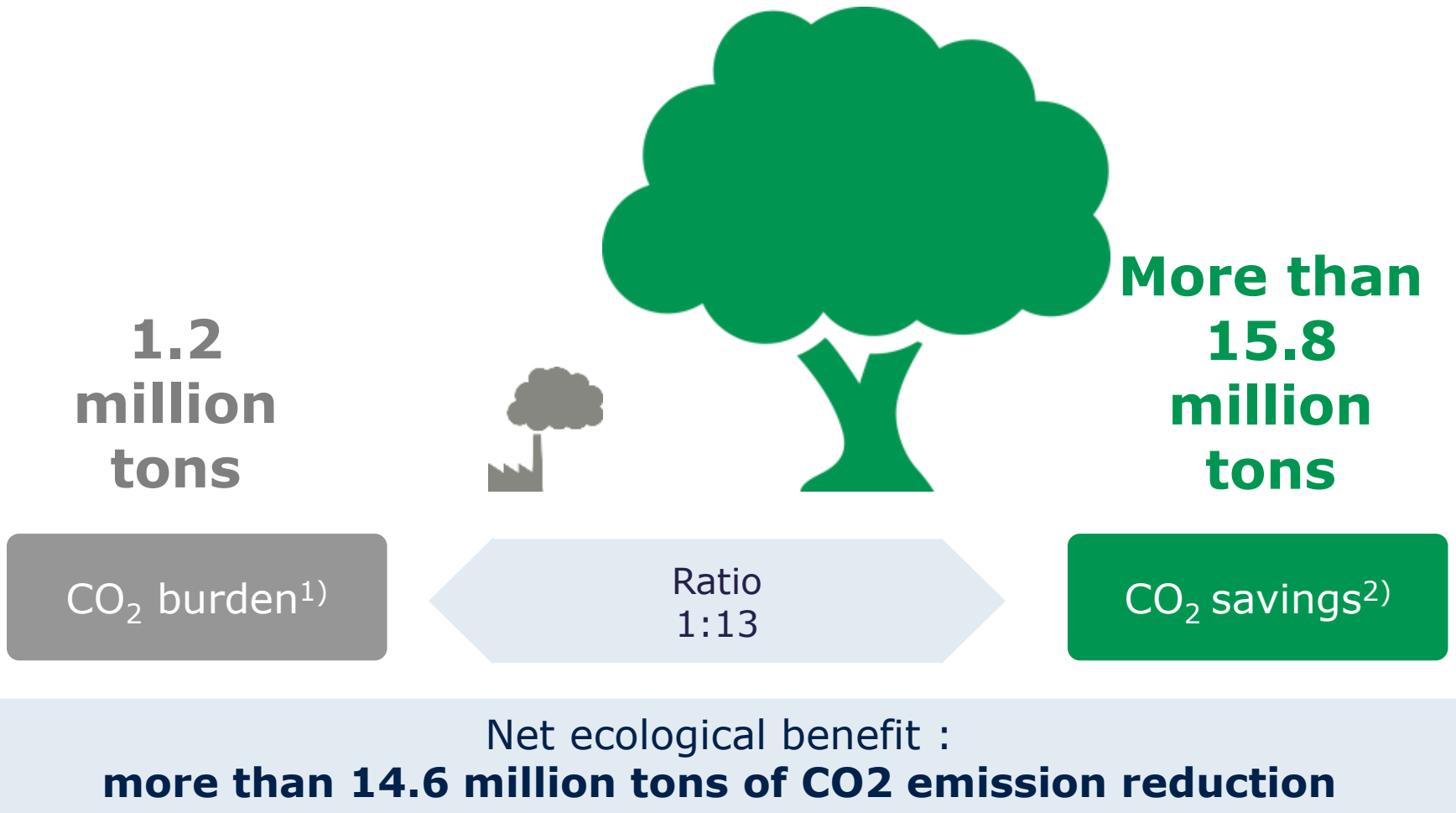
- We consume **33% less** water to manufacture 1sqcm wafer than the global average[1].

- We consume **42% less** energy to manufacture 1sqcm wafer than the global average[1].

- We generate **50% less** waste to manufacture 1sqcm wafer than the global average[1].

* ISO 50001 in major EU sites
[1] According to "World Semiconductor Council"

Our CO_2 Balance: Emission Reduction Enabled by Our Products and Solutions

1.2 million tons

More than 15.8 million tons

CO_2 burden[1]	Ratio 1:13	CO_2 savings[2]

Net ecological benefit :
more than 14.6 million tons of CO2 emission reduction

1) including manufacturing, transport, material, chemistry, emissions, water, waste and waste water, energy consumption; values are based on internal figures as well as official data for one year.
2) considering only automotive products, lighting, PC power supply, regenerative energy production (photovoltaic, wind) and drives, calculation based on average lifetime and Infineon market-share.

Integrated Business Continuity Management

Real Estate & Facility Management	Loss & Fraud Investigations	Environmental Affairs, Sustainability & Energy Management	Business & Operations Support
Asset Protection	**Business Continuity** ISO 27001 BS 25999 ISO 14001 OHSAS 18001 ISO 50001		Security & Crisis Management
Corporate Social Responsibility	Information Security & IT Security Management	Business Continuity Planning	Export Compliance